

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2000	(semiconductor or wafer) same chuck same (tape or pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:47
L2	939	1 and (polish\$3 or grind\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:35
L3	1932	(semiconductor or wafer) same (\$4holder) same (tape or pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:28
L4	1172	3 and (polish\$ or grind\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:28
L6	68	2 and cleaning and drying	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:35
L7	112	(semiconductor or wafer) same chuck same (mesh)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/11 13:55